TLP130

TOSHIBA Photocoupler IRED & Photo-Transistor

TLP130

Programmable Controllers AC / DC-Input Module Telecommunication

TOSHIBA

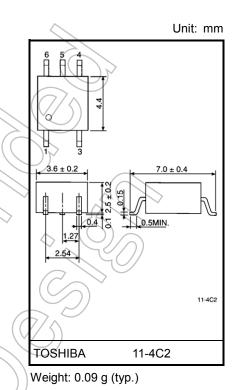
The TOSHIBA mini flat coupler TLP130 is a small outline coupler, suitable for \gtrsim surface mount assembly.

TLP130 consists of a photo transistor, optically coupled to two infrared emitting diodes connected inverse parallel, and operate directly by AC input current.

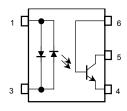
- Collector-emitter voltage: 80 V (min)
- Current transfer ratio: 50 % (min)
 Rank GB: 100 % (min)
- Isolation voltage: 3750 Vrms (min)
- UL-recognized: UL 1577, File No.E67349
- cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
- Current transfer ratio

	Current Transf		
Classification	I _F = ±5mA, V _C	Marking of Classification	
	Min	Max	
Standard	50	600	Blank, GB
Rank GB	100	600	GB

Note: Application type name for certification test, please use standard product type name, i.e. TLP130(GB): TLP130



Pin Configurations (top view)



1 : Anode, Cathode

- 3 : Cathode, Anode
- 4 : Emitter
- 5 : Collector
- 6 : Base

Start of commercial production 1988-04

Absolute Maximum Ratings (Ta = 25°C)

	Cha	Symbol	Rating	Unit	
	Forward current		I _{F(RMS)}	50	mA
	Forward current derating	(Ta≥53°C)	ΔI _F /°C	-0.7	mA/°C
ED	Peak forward current 100pps)	(100 μ s pulse,	IFP	1	А
_	Diode power dissipation		PD	100	mW
	Diode power dissipation der	ating (Ta ≥ 53°C)	ΔP _D /°C	-1.39	mW/°C
	Junction temperature		тј <	125	°C
	Collector-emitter voltage		VCEO	80	V
	Collector-base voltage		Vсво	80	V
Detector	Emitter-collector voltage		VECO	7	Y
	Emitter-base voltage		VEBO	7	\sim
	Collector current		lc	50	mA
ð	Peak collector current	(10 ms pulse, 100 pps)	IGP	100	mA
_	Power dissipation		Pc	150	mW
	Power dissipation derating	(Ta ≥ 25°C)	ΔP _C /°C	-1.5	mW/°C
	Junction temperature		Тj	125	°C
Stor	rage temperature range		T _{stg}	-55 to 125	°C
Оре	erating temperature range	$\langle \langle \rangle \rangle$	Topr	-55 to 100	°C
Lea	Lead soldering temperature (10 s)			260	°C
Tota	al package power dissipation		PT	200	mW
Tota	al package power dissipation	derating (Ta ≥ 25°C)	ΔP _T /°C	-2.0	mW/°C
Isola	ation voltage	(AC, 60 s, R.H. ≤ 60 %) (Note 1)	BVs	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: Device considered a two terminal device: Pins 1 and 3 shorted together and pins 4, 5 and 6 shorted together.

Recommended Operating Conditions

Characteristics	Symbol	Min	Тур.	Max	Unit
Supply voltage	Vcc	_	5	48	V
Forward current			16	25	mA
Collector current	IC		1	10	mA
Operating temperature	Topr	-25		85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

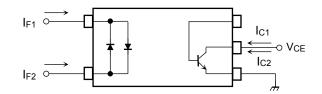
Electrical Characteristics (Ta = 25°C)

	Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Ω	Forward voltage	VF	I _F = ±10 mA	1.0	1.15	1.3	V
LED	Capacitance	CT	V = 0 V, f = 1 MHz		60	_	pF
	Collector-emitter breakdown voltage	V(BR)CEO	IC = 0.5 mA	80	K	_	V
	Emitter-collector breakdown voltage	V _{(BR)ECO}	I _E = 0.1 mA	7	(\mathbf{I})	1	V
Detector	Collector-base breakdown voltage	V _(BR) CBO	I _C = 0.1 mA	80	\sim	_	V
	Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = 0.1 mA	V,		_	V
	Collector dark current	lana	V _{CE} = 48 V	X	10	100	nA
		ICEO	V _{CE} = 48 V, Ta = 85 °C	J,	2	50	μA
	Collector dark current	ICER	V _{CE} = 48 V, Ta = 85 °C R _{BE} = 1 MΩ		0.5	10	μΑ
	Collector dark current	ICBO	V _{CB} = 10 V	_	0.1	X	nA
	DC forward current gain	hFE	V _{CE} = 5 V, I _C = 0.5 mA	\Diamond	400		_
	Capacitance collector to emitter	C _{CE}	V = 0 V, f = 1 MHz		10	-10/	pF

Coupled Electrical Characteristics (Ta = 25°C)

600	Unit %
%	%
	%
	%
- /	%
— h	μA
0.4	
\	V
0.4	
10 µ,	μA
3 –	_

Note 1:
$$I_C(ratio) = \frac{I_C2(I_F = I_{F2}, V_{CE} = 5V)}{I_C1(I_F = I_{F1}, V_{CE} = 5V)}$$



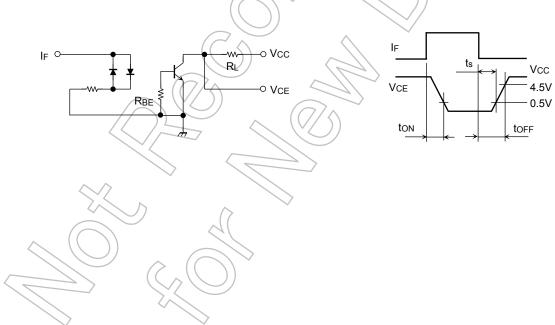
Isolation Characteristics (Ta = 25°C)

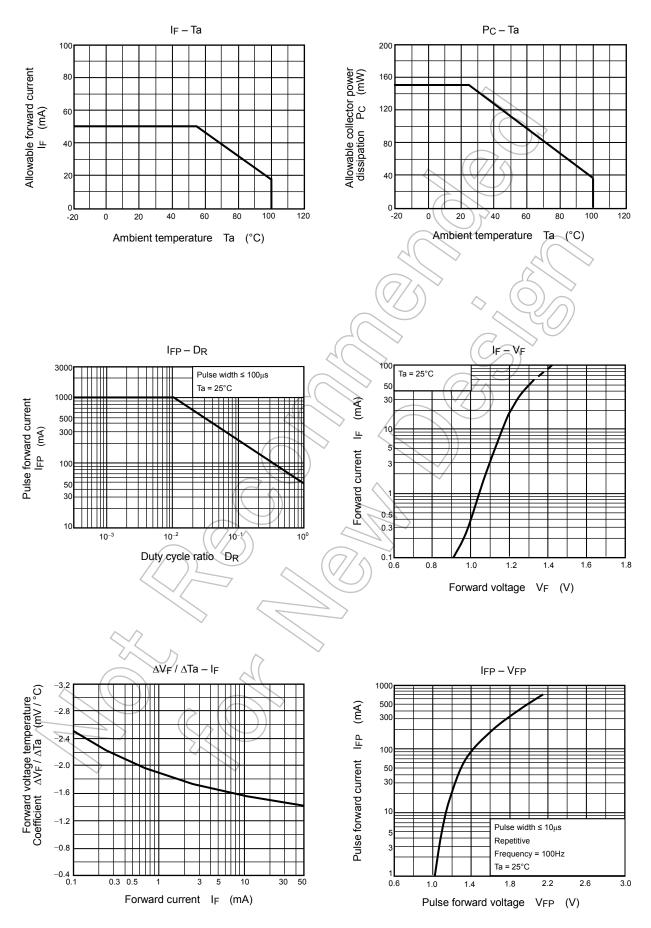
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance input to output	CS	V _S = 0 V, f = 1 MHz	—	0.8	_	pF
Isolation resistance	Rs	V _S = 500 V, R.H. ≤ 60 %	5×10 ¹⁰	10 ¹⁴	_	Ω
Isolation voltage	BVS	AC, 60 s	3750	1		Vrms

Switching Characteristics (Ta = 25°C)

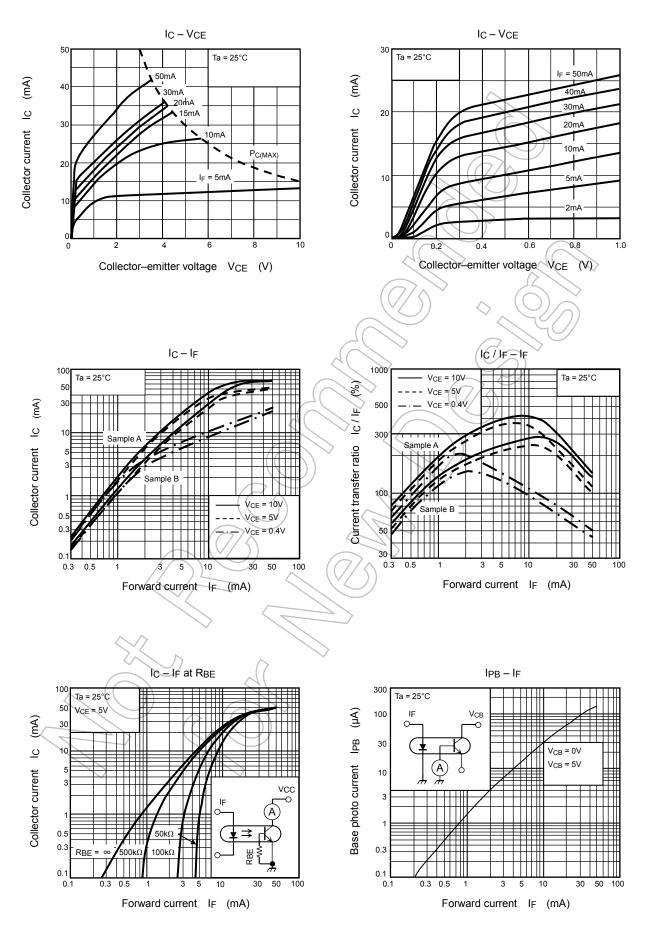
				\sum		
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Rise time	tr		Y	2	_	
Fall time	tf	V _{CC} = 10 V, I _C = 2 mA		3		
Turn-on time	t _{on}	R _L = 100 Ω	~_	3	1	μs
Turn-off time	t _{off}		_	3	$\langle \rangle$	
Turn-on time	ton	RL = 1.9 kΩ (Fig.1)	_>	2	1	
Storage time	ts	R _{BE} = OPEN	- (25	9	μS
Turn-off time	tOFF	$V_{CC} = 5 V$, $I_F = \pm 16 mA$	-C	40		
Turn-on time	ton	RL = 1.9 kΩ (Fig.1)		2	-	
Storage time	ts	R _{BE} = 220 kΩ	$(H \land$	20	_	μS
Turn-off time	toff	VCC = 5 V, IF = ±16 mA		30	_	

Fig. 1 Switching time test circuit





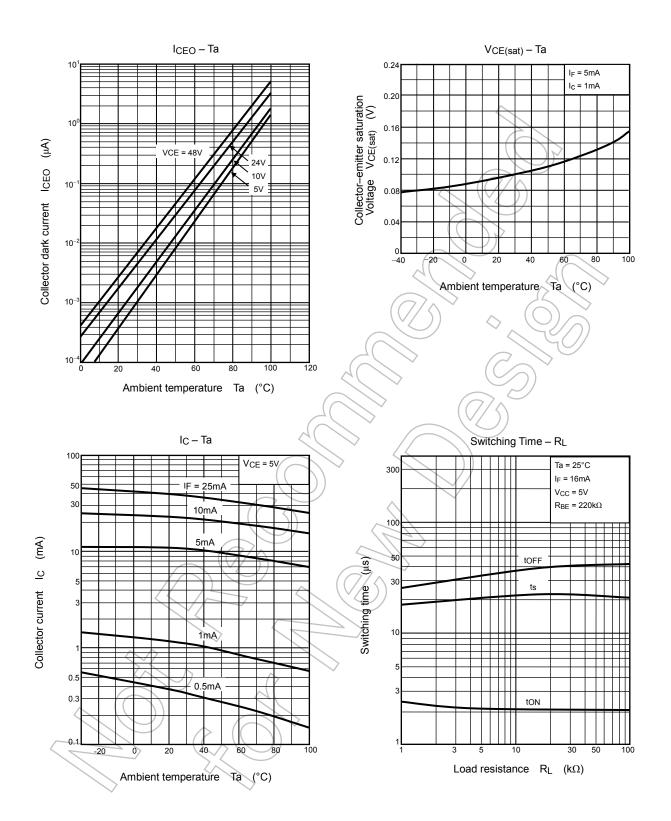
NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted. 5



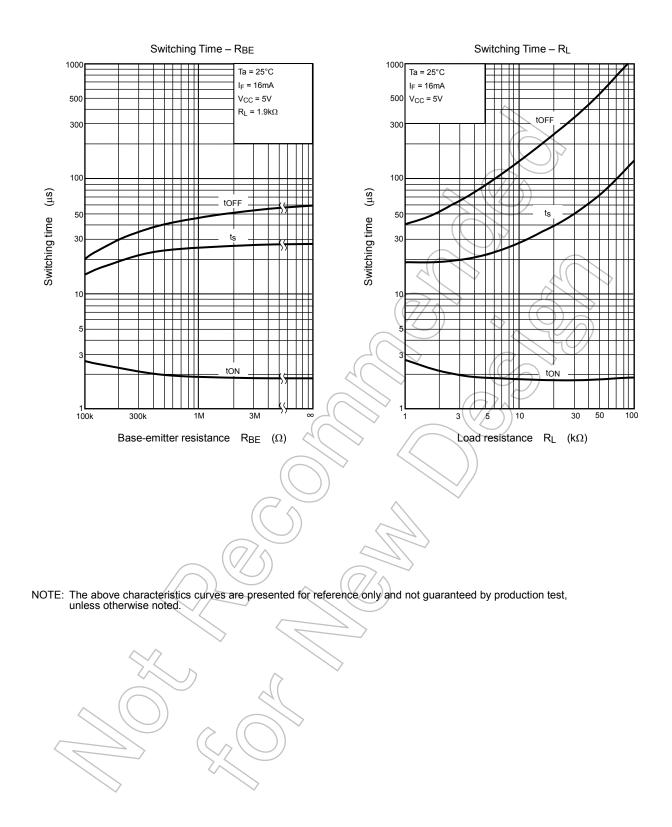
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